



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2023-11-09
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G071RBT3	E45W*460XXXY	A	9991	2023-11-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	349.70	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10	64	L bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E45W*460XXXY				9999999.0	999997.1				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	5.199	mg	Supplier	die	Silicon (Si)	7440-21-3		5.002	mg	962108	14304				
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	1731	26				
				Supplier	metallization	Copper (Cu)	7440-50-8		0.084	mg	16157	240				
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.027	mg	5193	77				
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	192	3				
				Supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	192	3				
				Supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	4039	60				
				Supplier	Passivation	Silicon Oxide	7631-86-9		0.054	mg	10387	154				
				Leadframe (C7025 + Ag)	Copper & its alloys	100.000	mg	Supplier	Leadframe	Copper (Cu)	7440-50-8		91.900	mg	919000	262797
								Supplier	Leadframe	Nickel (Ni)	7440-02-0		3.100	mg	31000	8865
Supplier	Leadframe	Silicon (Si)	7440-21-3						1.200	mg	12000	3432				
Supplier	Leadframe	Magnesium (Mg)	7439-95-4						0.300	mg	3000	858				
Supplier	Leadframe	Silver (Ag)	7440-22-4						3.500	mg	35000	10009				
Glue Epoxy (CRM-1076WA)	Precious metals	1.000	mg	Supplier	Glue or tape	Silver Powder	7440-22-4		0.764	mg	764000	2185				
				Supplier	Glue or tape	Bisphenol F Type Epoxy Resin	9003-36-5		0.030	mg	30000	86				
				Supplier	Glue or tape	Epoxy resin	Proprietary		0.060	mg	60000	172				
				Supplier	Glue or tape	Hardener	Proprietary		0.030	mg	30000	86				
				Supplier	Glue or tape	Ethylene dimethacrylate	97-80-5		0.075	mg	75000	214				
				Supplier	Glue or tape	1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0		0.030	mg	30000	86				
				Supplier	Glue or tape	Dicyandiamide	461-58-5		0.006	mg	5500	16				
				Supplier	Glue or tape	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8		0.006	mg	5500	16				
Bonding wire (Au 0.8 mils)	Precious metals	1.400	mg	Supplier	Bonding wire	Gold (Au)	7440-57-5		1.384	mg	988500	3957				
				Supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.016	mg	11500	46				
Encapsulation (EME-G6315H)	M-011 Other inorganic materials	228.300	mg	Supplier	Molding Compound	2,2'-(3,3',5,5'-Tetramethyl-(1,1'-biphenyl))-4,4'	85954-11-6		9.132	mg	40000	26114				
				Supplier	Molding Compound	Epoxy resin	Proprietary		4.566	mg	20000	13057				
				Supplier	Molding Compound	Phenol Resin	Proprietary		17.123	mg	75000	48963				
				Supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		161.979	mg	709500	463194				
				Supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		34.245	mg	150000	97927				
External Plating (Sn)	M-011 Other inorganic materials	13.800	mg	Supplier	Molding Compound	Carbon black	1333-86-4		1.256	mg	5500	3591				
				Supplier	Matte Sn	Tin (Sn)	7440-31-5		13.799	mg	999900	39458				
				Supplier	Matte Sn	Impurities	-		0.001	mg	100	4				